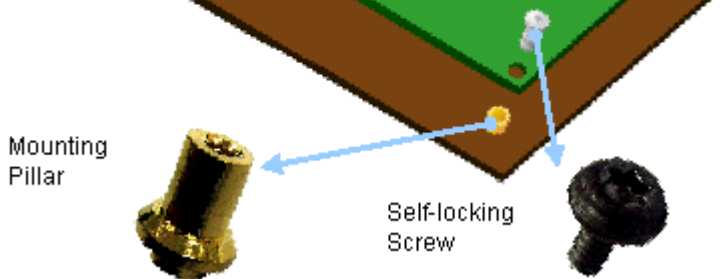


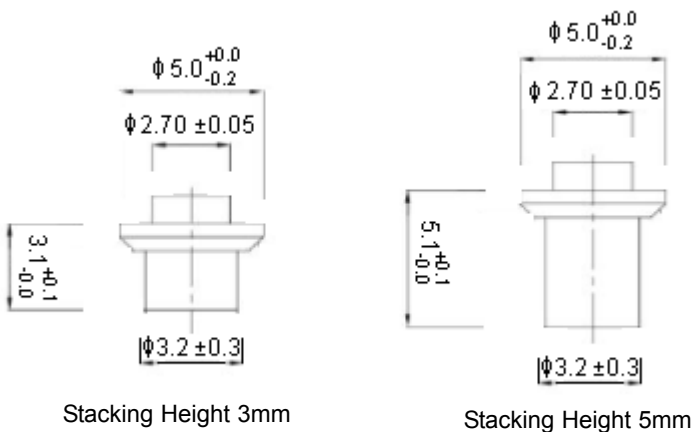
## Features and Application:

- Enhance the grounding of the cinterion module to the PCB.
- Simple production process.
  1. SMT process to solder mounting pillars to the PCB.
  2. Self-locking screw solution for mounting the module on to the mounting pillars.
- Flexible solution with easy access to remove the module.



## Mounting Pillar and Screw Specifications:

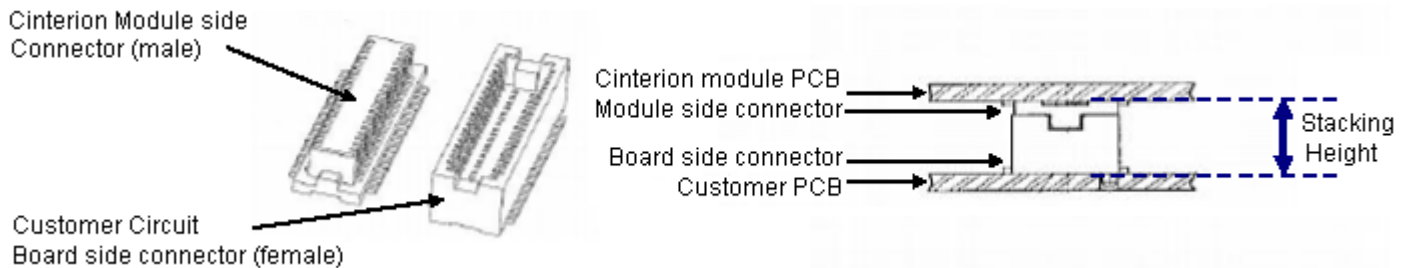
Inner raw material	: Ms58 (C3602) copper alloy.
First plating layer	: Copper flash.
Second plating layer	: Nickel plating (1.0µm).
Third plating layer	: Gold plating (0.8µm).
Weight	: 0.35g.



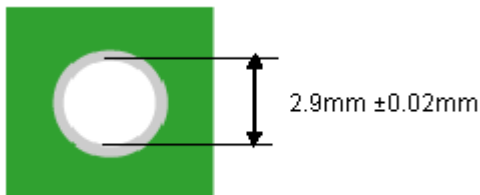
Dimensions: Millimetres

## Stacking Height Definition

When both connectors are mated together:



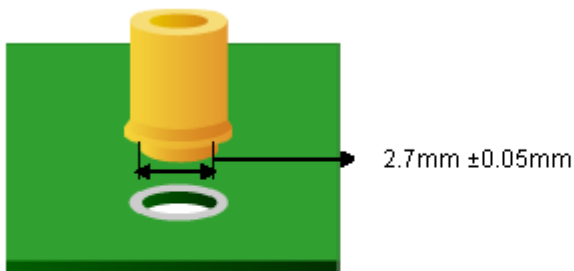
## Mounting Instructions



Plated PCB hole size to accommodate the solder mounting pillars  
PCB footprint for hole locations

: 2.9mm ±0.02mm.  
: Please refer to the cinterion module datasheet.

Step1: SMT process for mounting pillars

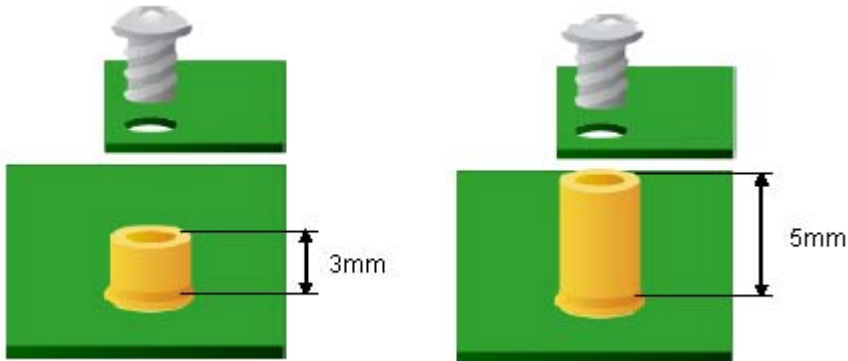


Solder paste applied to pad on PCB



Solder the Mounting Pillar in place using standard surface mount Techniques

Step2: Mounting the module with self-locking screws



The torque values for tightening the screws are:

- Recommended torque for tightening :1.50kgf.cm.
- Maximum torque for tightening :1.70 to 1.80kgf.cm.

## Part Number Table

Description	Part Number
Pillar for Cinterion Module, 3mm	R-14-0076
Pillar for Cinterion Module, 5mm	R-14-0077

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